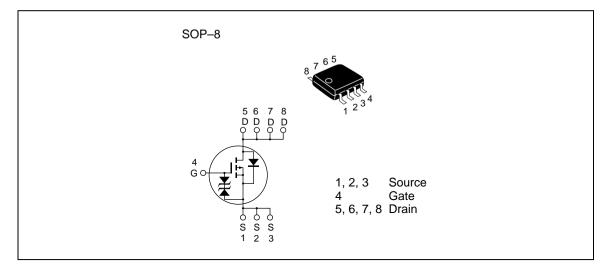
Silicon P Channel Power MOS FET High Speed Power Switching HITACHI

ADE-208-475 D (Z) 5th. Edition February 1999

Features

- Low on-resistance
- Capable of 2.5 V gate drive
- Low drive current
- High density mounting

Outline



Absolute Maximum Ratings (Ta = 25° C)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	- 20	V	
Gate to source voltage	V _{GSS}	± 10	V	
Drain current	I _D	- 5.5	А	
Drain peak current	Note1 I _{D(pulse)}	- 44	А	
Body-drain diode reverse drain current	I _{DR}	- 5.5	А	

Item	Symbol	Ratings	Unit	
Channel dissipation	Pch Note2	2.5	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

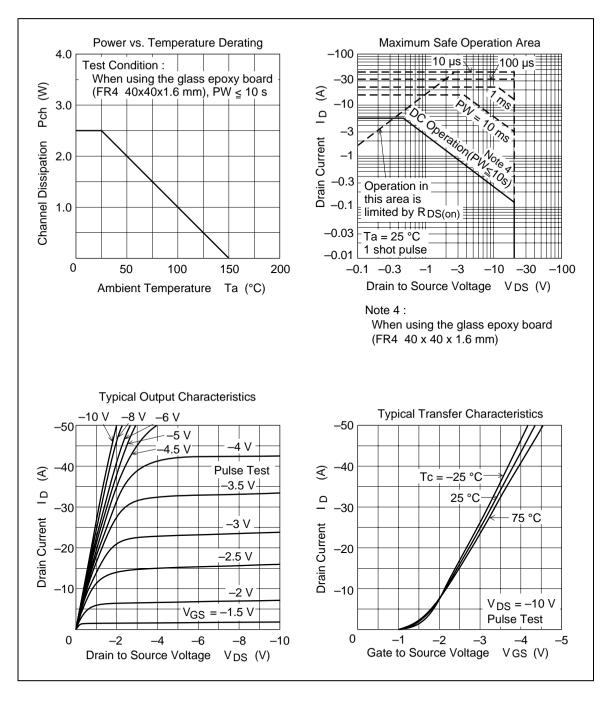
Note: 1. $PW \le 10\mu s$, duty cycle $\le 1 \%$ When using the glass epoxy board (FR4 40 x 40 x 1.6 mm), $PW \le 10s$

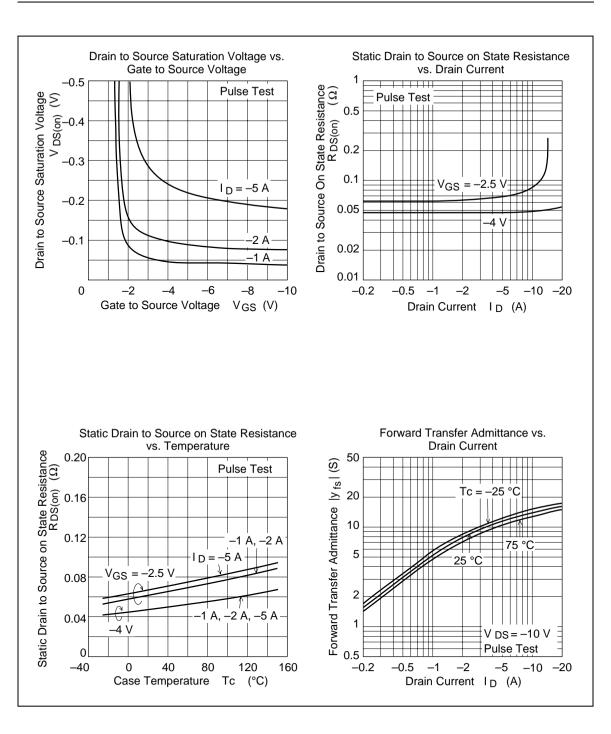
Electrical Characteristics (Ta = 25° C)

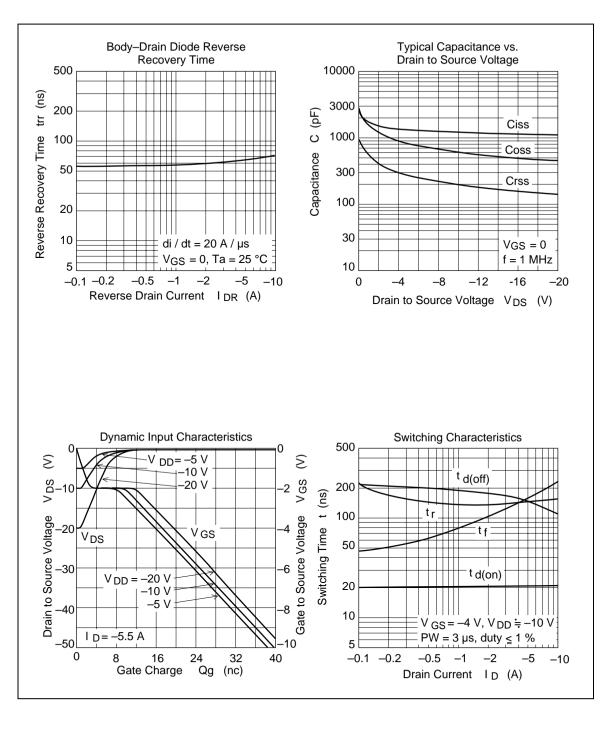
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DS} s	- 20	_		V	$I_{D} = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GS} S	± 10	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	—	—	± 10	μΑ	$V_{GS} = \pm 8 V, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	—	—	- 10	μΑ	$V_{DS} = -20 V, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	- 0.5	_	– 1.5	V	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ mA}$
Static drain to source on state	R _{DS(on)}	—	0.048	0.060	Ω	$I_D = -3 \text{ A}, V_{GS} = -4 \text{ V}^{\text{Note3}}$
resistance	R _{DS(on)}	_	0.065	0.085	Ω	$I_D = -3 \text{ A}, V_{GS} = -2.5 \text{ V}$ Note3
Forward transfer admittance	y _{fs}	6	9.5		S	$I_D = -3 \text{ A}, V_{DS} = -10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss	_	1200	—	pF	V _{DS} = - 10 V
Output capacitance	Coss	_	630	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	200	_	pF	f = 1MHz
Turn-on delay time	t _{d(on)}	—	20	—	ns	$V_{GS} = -4 V, I_{D} = -3 A$
Rise time	t _r	_	120		ns	V _{DD} @ – 10 V
Turn-off delay time	t _{d(off)}		175		ns	
Fall time	t _f	—	140	—	ns	
Body-drain diode forward voltage	V_{DF}		- 0.9	- 1.4	V	$IF = -5.5 \text{ A}, V_{GS} = 0^{\text{Note3}}$
Body–drain diode reverse recovery time	t _{rr}		65		ns	$IF = -5.5 \text{ A}, V_{GS} = 0$ diF/ dt = 20 A/ μ s

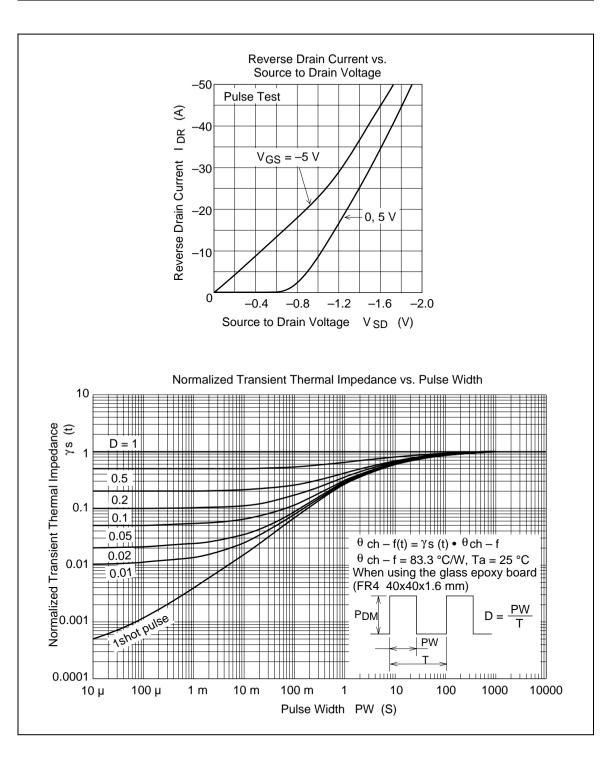
Note: 3. Pulse test

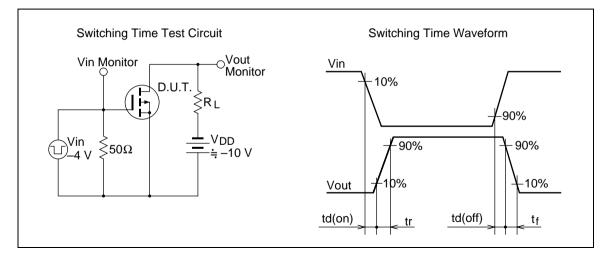
Main Characteristics





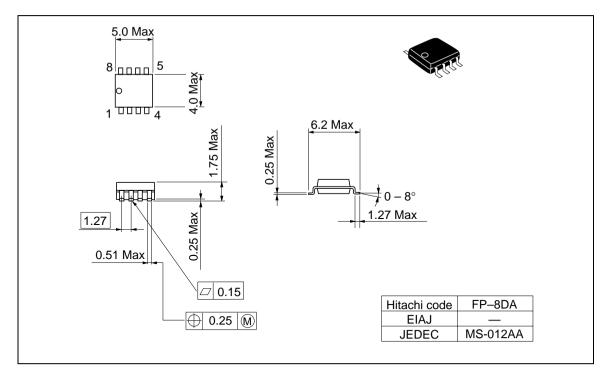






Package Dimensions

Unit: mm



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